



TPS22918 5.5V、2A、导通电阻为 52mΩ 的负载开关

1 特性

- 集成单通道负载开关
- 环境工作温度范围: -40°C 至 $+105^{\circ}\text{C}$
- 输入电压范围: 1V 至 5.5V
- 导通电阻 (R_{ON})
 - $R_{\text{ON}} = 52\text{m}\Omega$ ($V_{\text{IN}} = 5\text{V}$ 时的典型值)
 - $R_{\text{ON}} = 53\text{m}\Omega$ ($V_{\text{IN}} = 3.3\text{V}$ 时的典型值)
- 2A 最大持续开关电流
- 低静态电流
 - $8.3\mu\text{A}$ ($V_{\text{IN}} = 3.3\text{V}$ 时的典型值)
- 低控制输入阈值, 允许使用 1V 或电压更高的 GPIO
- 可调节快速输出放电 (QOD)
- 可通过 CT 引脚配置的上升时间
- 小外形尺寸晶体管 (SOT-23)-6 封装 (DBV)
 - $2.90\text{mm} \times 2.80\text{mm}$, 间距为 0.95mm , 高度为 1.45mm (带引线)
- 静电放电 (ESD) 性能经测试符合 JESD 22 规范
 - $\pm 2\text{kV}$ 人体模型 (HBM) 和 $\pm 1\text{kV}$ 带电器件模型 (CDM)

2 应用

- 工业系统
- 机顶盒
- 血糖仪
- 电子销售终端

3 说明

TPS22918 是一款单通道负载开关, 可对上升时间和快速输出放电进行配置。此器件包括一个 N 沟道金属氧化物半导体场效应晶体管 (MOSFET), 可在 1V 至 5.5V 的输入电压范围内运行并可支持 2A 的最大持续电流。此开关由一个开关输入控制, 能够直接连接低电压控制信号。

该器件的可配置上升时间可大幅降低大容量负载电容所产生的浪涌电流, 从而降低或消除电源压降。

TPS22918 具有一个可配置的快速输出放电 (QOD) 引脚, 用于控制器件的下降时间, 以便针对掉电或排序进行灵活设计。

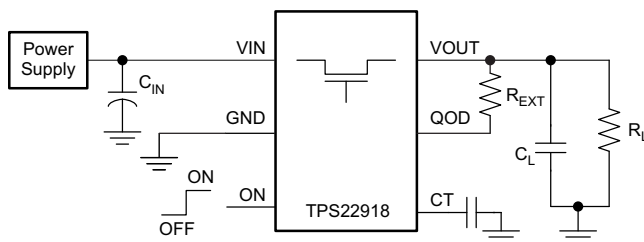
TPS22918 采用小型、带引线的 SOT-23 封装 (DBV), 方便对焊接点进行外观检查。该器件在自然通风环境下的额定运行温度范围为 -40°C 至 $+105^{\circ}\text{C}$ 。

器件信息 (1)

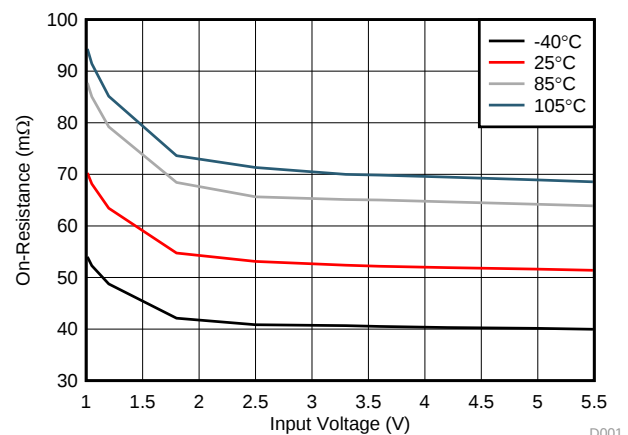
部件号	封装	封装尺寸 (标称值)
TPS22918	SOT-23 (6)	$2.90\text{mm} \times 1.60\text{mm}$

(1) 如需了解所有可用封装, 请见数据表末尾的可订购产品附录。

简化电路原理图



R_{ON} 与 V_{IN} 间的关系 ($I_{\text{OUT}} = -200\text{mA}$)
典型值



D001



目录

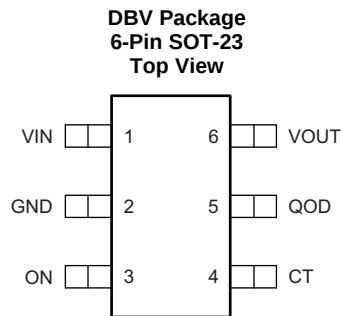
1	特性	1	8.4	Device Functional Modes.....	15
2	应用	1	9	Application and Implementation	16
3	说明	1	9.1	Application Information.....	16
4	修订历史记录	2	9.2	Typical Application	16
5	Pin Configuration and Functions	3	10	Power Supply Recommendations	20
6	Specifications	4	11	Layout	20
6.1	Absolute Maximum Ratings	4	11.1	Layout Guidelines	20
6.2	ESD Ratings	4	11.2	Layout Example	21
6.3	Recommended Operating Conditions.....	4	11.3	Thermal Considerations.....	21
6.4	Thermal Information	4	12	器件和文档支持	22
6.5	Electrical Characteristics.....	5	12.1	器件支持	22
6.6	Switching Characteristics	6	12.2	文档支持	22
6.7	Typical Characteristics	7	12.3	社区资源	22
7	Parameter Measurement Information	11	12.4	商标	22
8	Detailed Description	12	12.5	静电放电警告	22
8.1	Overview	12	12.6	Glossary	22
8.2	Functional Block Diagram	12	13	机械、封装和可订购信息	22
8.3	Feature Description.....	13			

4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Original (February 2016) to Revision A	Page
• 已将器件状态由“产品预览”更改为“量产数据”	1

5 Pin Configuration and Functions



Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	VIN	I	Switch input. Place ceramic bypass capacitor(s) between this pin and GND. See the Detailed Description section for more information.
2	GND	—	Device ground.
3	ON	I	Active high switch control input. Do not leave floating.
4	CT	O	Switch slew rate control. Can be left floating. See the Feature Description section for more information.
5	QOD	O	Quick Output Discharge pin. This functionality can be enabled in one of three ways. - Placing an external resistor between VOUT and QOD - Tying QOD directly to VOUT and using the internal resistor value (R_{PD}) - Disabling QOD by leaving pin floating See the Quick Output Discharge (QOD) section for more information.
6	VOUT	O	Switch output.

6 Specifications

6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) ⁽¹⁾ ⁽²⁾

		MIN	MAX	UNIT
V _{IN}	Input voltage	–0.3	6	V
V _{OUT}	Output voltage	–0.3	6	V
V _{ON}	ON voltage	–0.3	6	V
I _{MAX}	Maximum continuous switch current, ambient temperature = 70°C		2	A
I _{PLS}	Maximum pulsed switch current, pulse < 300 μs, 2% duty cycle		2.5	A
T _J	Maximum junction temperature		125	°C
T _{stg}	Storage temperature	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{IN}	Input voltage		0	5.5	V
V _{ON}	ON voltage		0	5.5	V
V _{OUT}	Output voltage			V _{IN}	V
V _{IH, ON}	High-level input voltage, ON	V _{IN} = 1 V to 5.5 V	1	5.5	V
V _{IL, ON}	Low-level input voltage, ON	V _{IN} = 1 V to 5.5 V	0	0.5	V
T _A	Operating free-air temperature range ⁽¹⁾		–40	105	°C
C _{IN}	Input Capacitor		1 ⁽²⁾		μF

- (1) In applications where high power dissipation and/or poor package thermal resistance is present, the maximum ambient temperature may have to be derated. Maximum ambient temperature [T_{A(MAX)}] is dependent on the maximum operating junction temperature [T_{J(MAX)}], the maximum power dissipation of the device in the application [P_{D(MAX)}], and the junction-to-ambient thermal resistance of the part/package in the application (θ_{JA}), as given by the following equation: T_{A(MAX)} = T_{J(MAX)} – (θ_{JA} × P_{D(MAX)}).

- (2) Refer to [Application and Implementation](#) section

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TPS22918	UNIT
		DBV (SOT-23)	
		6 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	183.2	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	151.6	°C/W
R _{θJB}	Junction-to-board thermal resistance	34.1	°C/W
ψ _{JT}	Junction-to-top characterization parameter	37.2	°C/W
ψ _{JB}	Junction-to-board characterization parameter	33.6	°C/W

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

Unless otherwise noted, the specification in the following table applies over the full ambient operating temperature $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$. Typical values are for $T_A = 25^{\circ}\text{C}$.

PARAMETER	TEST CONDITIONS	T_A	MIN	TYP	MAX	UNIT
$I_{Q, VIN}$ Quiescent current	$V_{ON} = 5\text{ V}, I_{OUT} = 0\text{ A}$	$V_{IN} = 5.5\text{ V}$	$-40^{\circ}\text{C to } +105^{\circ}\text{C}$	9.2	16	μA
		$V_{IN} = 5\text{ V}$		8.7	16	
		$V_{IN} = 3.3\text{ V}$		8.3	15	
		$V_{IN} = 1.8\text{ V}$		10.2	17	
		$V_{IN} = 1.2\text{ V}$		9.3	16	
		$V_{IN} = 1\text{ V}$		8.9	15	
$I_{SD, VIN}$ Shutdown current	$V_{ON} = 0\text{ V}, V_{OUT} = 0\text{ V}$	$V_{IN} = 5.5\text{ V}$	$-40^{\circ}\text{C to } +105^{\circ}\text{C}$	0.5	5	μA
		$V_{IN} = 5\text{ V}$		0.5	4.5	
		$V_{IN} = 3.3\text{ V}$		0.5	3.5	
		$V_{IN} = 1.8\text{ V}$		0.5	2.5	
		$V_{IN} = 1.2\text{ V}$		0.4	2	
		$V_{IN} = 1\text{ V}$		0.4	2	
I_{ON} ON pin input leakage current	$V_{IN} = 5.5\text{ V}, I_{OUT} = 0\text{ A}$	$-40^{\circ}\text{C to } +105^{\circ}\text{C}$			0.1	μA
R_{ON} On-Resistance	$V_{IN} = 5.5\text{ V}, I_{OUT} = -200\text{ mA}$	25°C		51	59	$\text{m}\Omega$
		$-40^{\circ}\text{C to } +85^{\circ}\text{C}$			71	
		$-40^{\circ}\text{C to } +105^{\circ}\text{C}$			78	
	$V_{IN} = 5.0\text{ V}, I_{OUT} = -200\text{ mA}$	25°C		52	59	$\text{m}\Omega$
		$-40^{\circ}\text{C to } +85^{\circ}\text{C}$			71	
		$-40^{\circ}\text{C to } +105^{\circ}\text{C}$			79	
	$V_{IN} = 4.2\text{ V}, I_{OUT} = -200\text{ mA}$	25°C		52	59	$\text{m}\Omega$
		$-40^{\circ}\text{C to } +85^{\circ}\text{C}$			71	
		$-40^{\circ}\text{C to } +105^{\circ}\text{C}$			79	
	$V_{IN} = 3.3\text{ V}, I_{OUT} = -200\text{ mA}$	25°C		53	59	$\text{m}\Omega$
		$-40^{\circ}\text{C to } +85^{\circ}\text{C}$			71	
		$-40^{\circ}\text{C to } +105^{\circ}\text{C}$			80	
	$V_{IN} = 2.5\text{ V}, I_{OUT} = -200\text{ mA}$	25°C		53	61	$\text{m}\Omega$
		$-40^{\circ}\text{C to } +85^{\circ}\text{C}$			75	
		$-40^{\circ}\text{C to } +105^{\circ}\text{C}$			80	
	$V_{IN} = 1.8\text{ V}, I_{OUT} = -200\text{ mA}$	25°C		55	65	$\text{m}\Omega$
		$-40^{\circ}\text{C to } +85^{\circ}\text{C}$			79	
		$-40^{\circ}\text{C to } +105^{\circ}\text{C}$			88	
	$V_{IN} = 1.2\text{ V}, I_{OUT} = -200\text{ mA}$	25°C		64	77	$\text{m}\Omega$
		$-40^{\circ}\text{C to } +85^{\circ}\text{C}$			88	
		$-40^{\circ}\text{C to } +105^{\circ}\text{C}$			104	
	$V_{IN} = 1.0\text{ V}, I_{OUT} = -200\text{ mA}$	25°C		71	85	$\text{m}\Omega$
		$-40^{\circ}\text{C to } +85^{\circ}\text{C}$			100	
		$-40^{\circ}\text{C to } +105^{\circ}\text{C}$			116	
V_{HYS} ON pin hysteresis	$V_{IN} = 1\text{ V to } 5.5\text{ V}$	$-40^{\circ}\text{C to } +105^{\circ}\text{C}$		107		mV
R_{PD} Output pull down resistance ⁽¹⁾	$V_{IN} = 5.0\text{ V}, V_{ON} = 0\text{ V}$	25°C		24		Ω
		$-40^{\circ}\text{C to } +105^{\circ}\text{C}$			30	
	$V_{IN} = 3.3\text{ V}, V_{ON} = 0\text{ V}$	25°C		25		
		$-40^{\circ}\text{C to } +105^{\circ}\text{C}$			35	
	$V_{IN} = 1.8\text{ V}, V_{ON} = 0\text{ V}$	25°C		45		
		$-40^{\circ}\text{C to } +105^{\circ}\text{C}$			60	

(1) Output pull down resistance varies with input voltage. Please see [Figure 7](#) for more information.

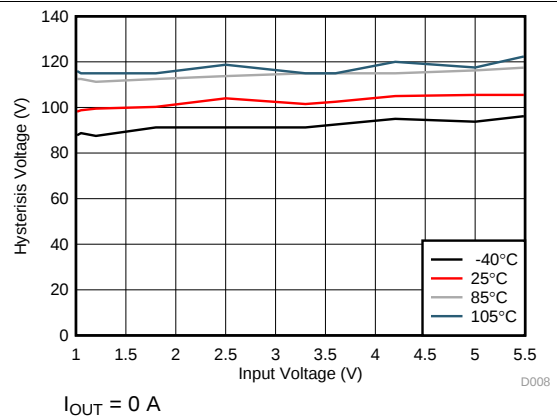
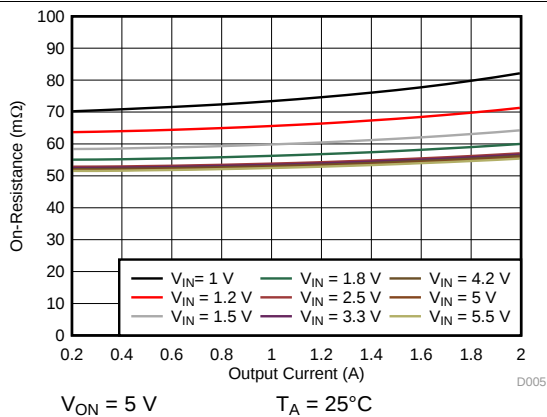
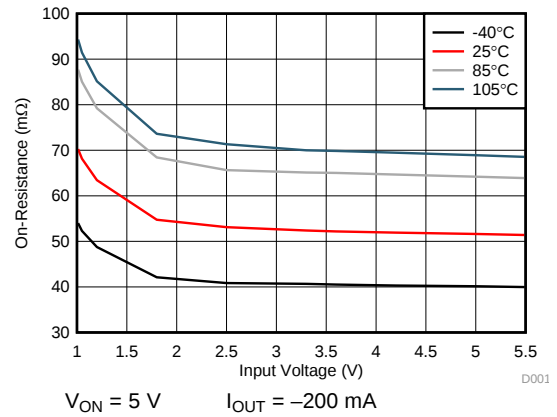
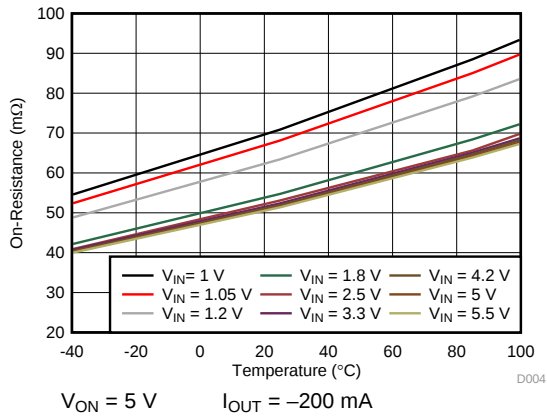
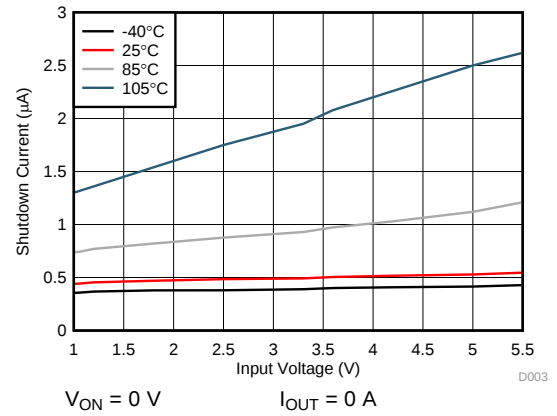
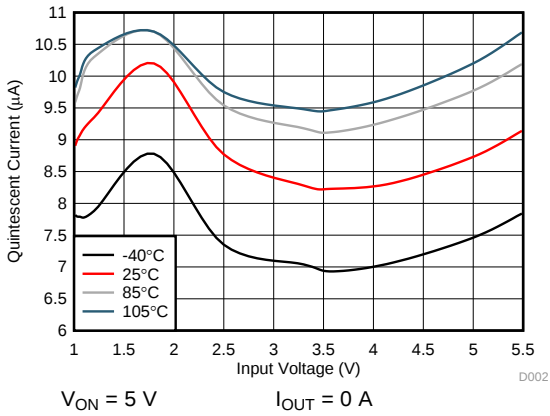
6.6 Switching Characteristics

Refer to the timing test circuit in [Figure 21](#) (unless otherwise noted) for references to external components used for the test condition in the switching characteristics table. Switching characteristics shown below are only valid for the power-up sequence where V_{IN} is already in steady state condition before the ON pin is asserted high. $V_{ON} = 5\text{ V}$, $T_A = 25\text{ }^{\circ}\text{C}$, QOD = Open.

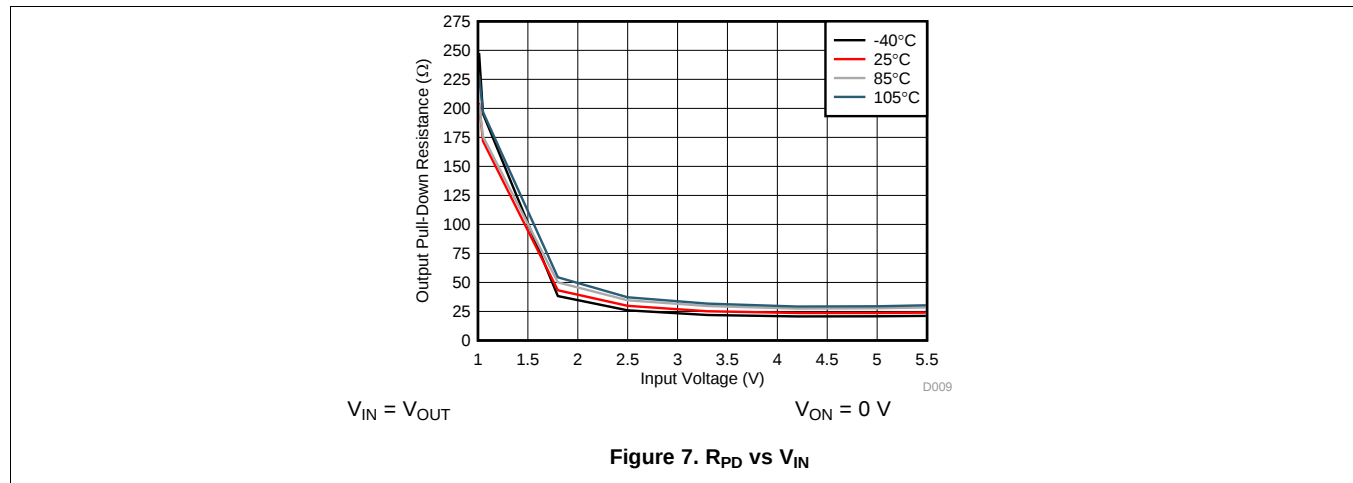
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{IN} = 5 V						
t _{ON}	Turn-on time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		1950		μs
t _{OFF}	Turn-off time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		2		
t _R	V _{OUT} rise time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		2540		
t _F	V _{OUT} fall time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		2		
t _D	Delay time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		690		
V _{IN} = 3.3 V						
t _{ON}	Turn-on time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		1430		μs
t _{OFF}	Turn-off time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		2		
t _R	V _{OUT} rise time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		1680		
t _F	V _{OUT} fall time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		2		
t _D	Delay time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		590		
V _{IN} = 1.8 V						
t _{ON}	Turn-on time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		965		μs
t _{OFF}	Turn-off time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		2		
t _R	V _{OUT} rise time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		960		
t _F	V _{OUT} fall time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		2		
t _D	Delay time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		480		
V _{IN} = 1 V						
t _{ON}	Turn-on time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		725		μs
t _{OFF}	Turn-off time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		3		
t _R	V _{OUT} rise time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		560		
t _F	V _{OUT} fall time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		2		
t _D	Delay time	R _L = 10 Ω, C _{IN} = 1 μF, C _L = 0.1 μF, CT = 1000 pF		430		

6.7 Typical Characteristics

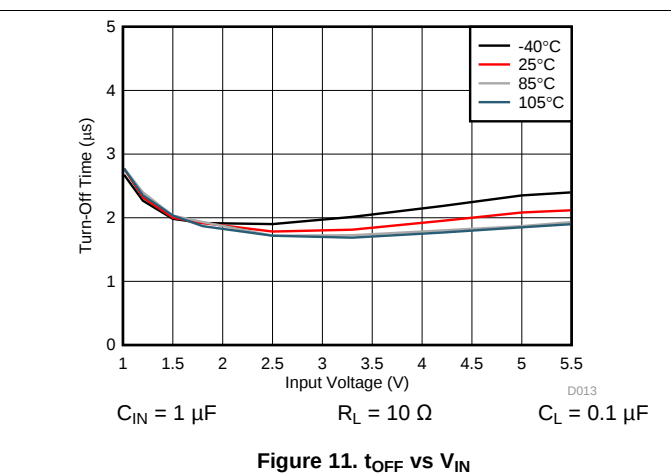
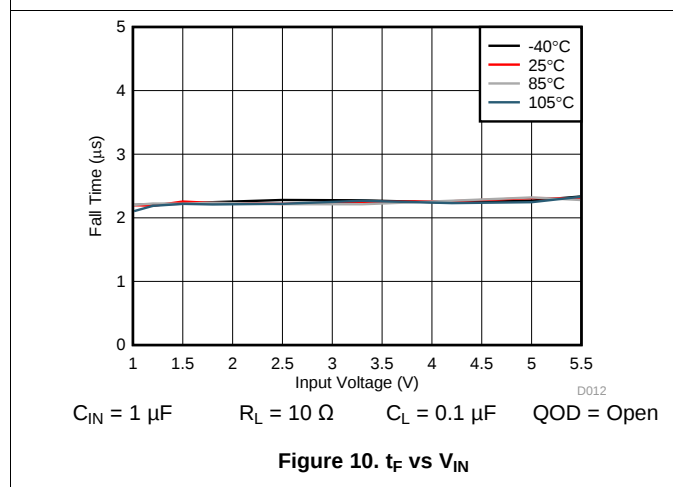
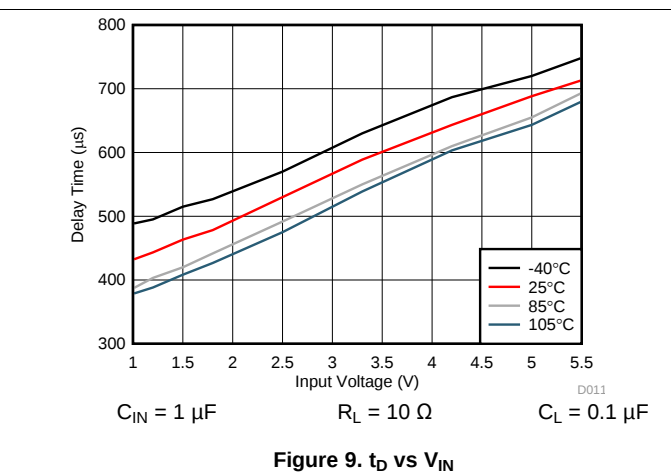
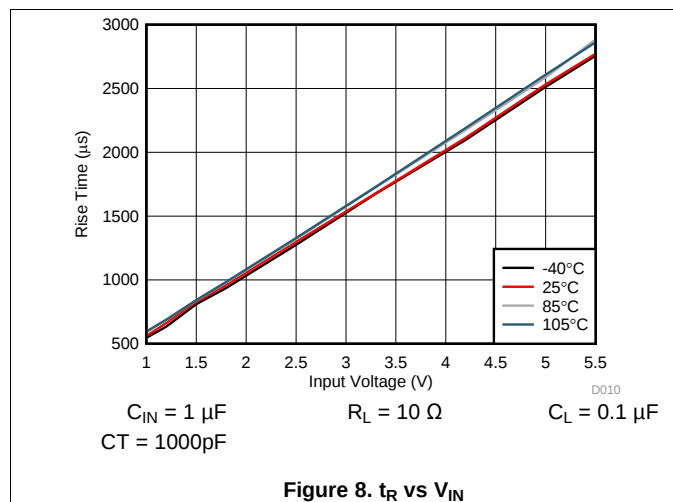
6.7.1 DC Characteristics



DC Characteristics (continued)



6.7.2 AC Characteristics



AC Characteristics (continued)

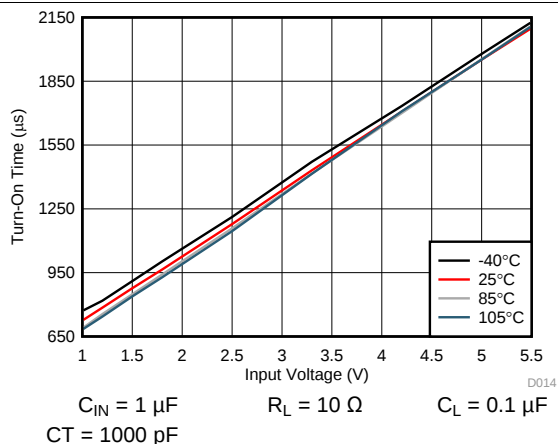


Figure 12. t_{ON} vs V_{IN}

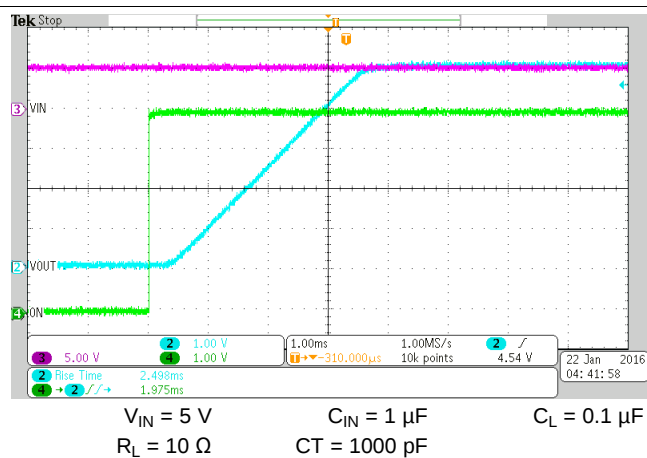


Figure 13. t_R at $V_{IN} = 5 \text{ V}$

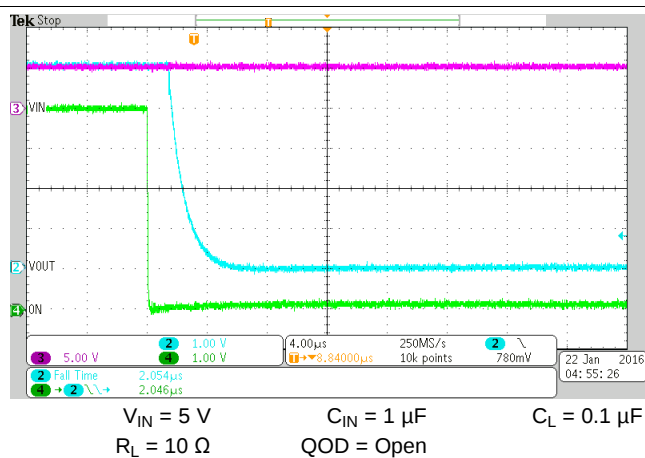


Figure 14. t_F at $V_{IN} = 5 \text{ V}$

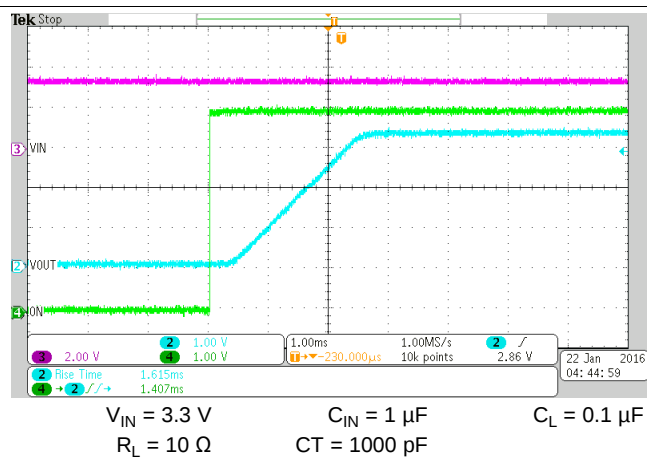


Figure 15. t_R at $V_{IN} = 3.3 \text{ V}$

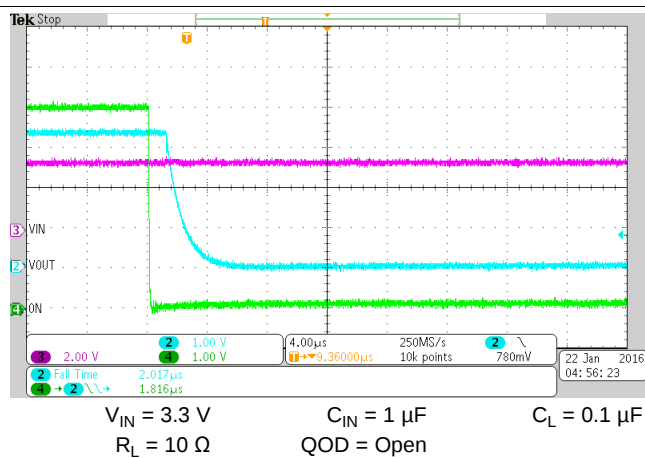
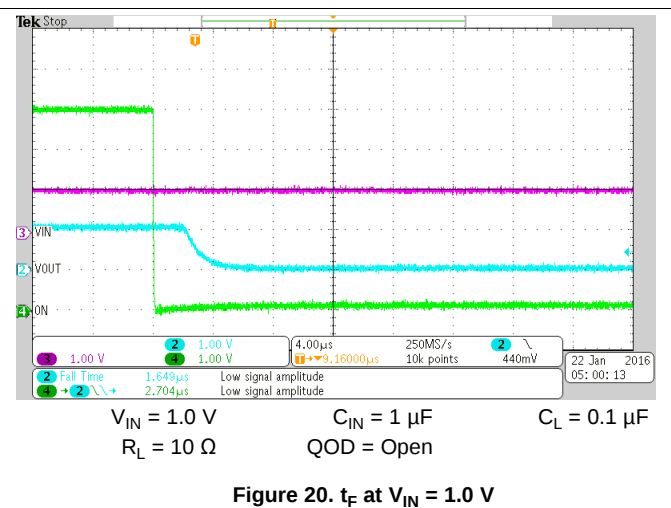
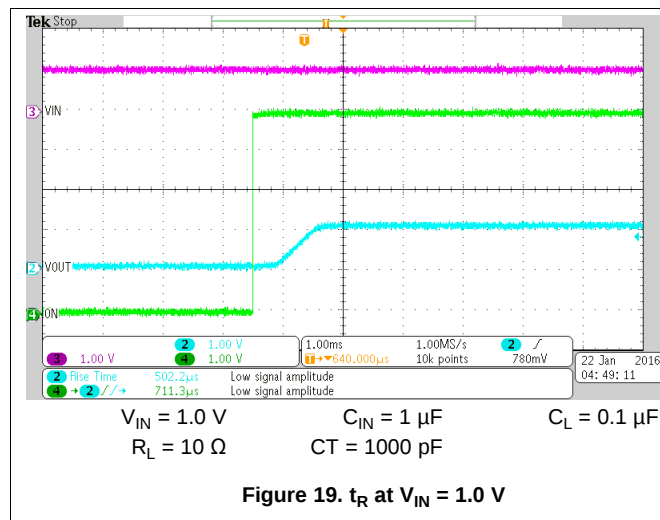
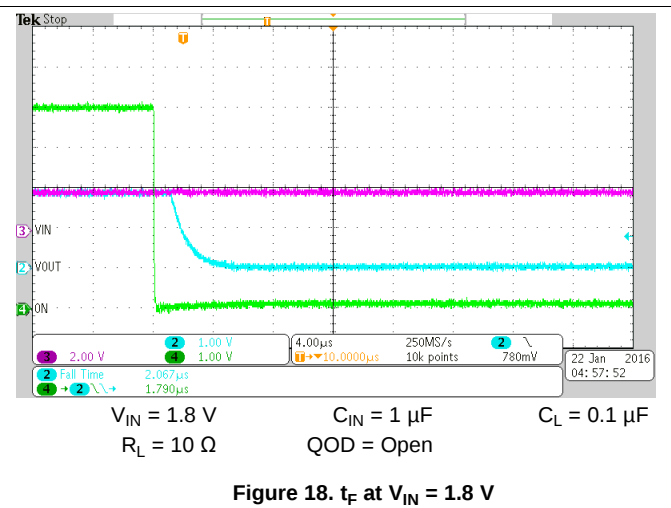
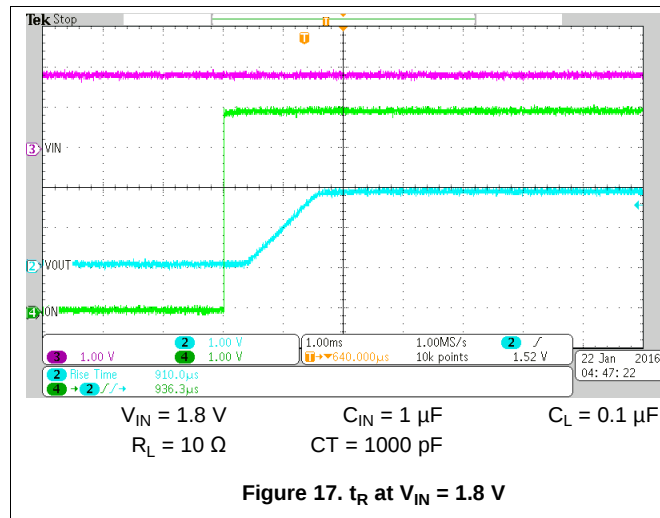
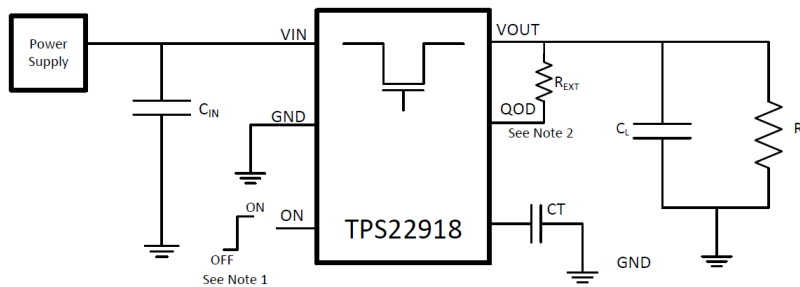


Figure 16. t_F at $V_{IN} = 3.3 \text{ V}$

AC Characteristics (continued)



7 Parameter Measurement Information



- (1) Rise and fall times of the control signal are 100 ns
- (2) Turn-off times and fall times are dependent on the time constant at the load. For TPS22918, the internal pull-down resistance R_{PD} is enabled when the switch is disabled. The time constant is $(R_{QOD} \parallel R_L) \times C_L$.

Figure 21. Test Circuit

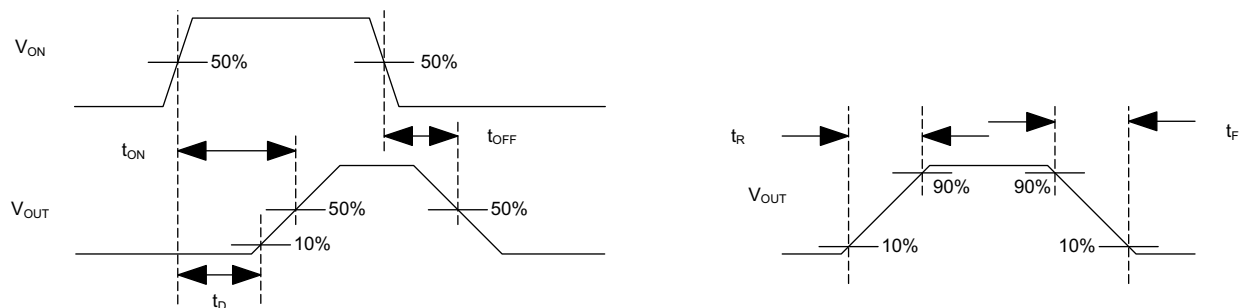


Figure 22. Timing Waveforms

8.3 Feature Description

8.3.1 On and Off Control

The ON pin controls the state of the switch. ON is active high and has a low threshold, making it capable of interfacing with low-voltage signals. The ON pin is compatible with standard GPIO logic threshold. It can be used with any microcontroller with 1 V or higher GPIO voltage. This pin cannot be left floating and must be driven either high or low for proper functionality.

8.3.2 Quick Output Discharge (QOD)

The TPS22918 includes a QOD feature. The QOD pin can be configured in one of three ways:

- QOD pin shorted to VOUT pin. Using this method, the discharge rate after the switch becomes disabled is controlled with the value of the internal resistance R_{PD} . The value of this resistance is listed in the [Electrical Characteristics](#) table.
- QOD pin connected to VOUT pin using an external resistor R_{EXT} . After the switch becomes disabled, the discharge rate is controlled by the value of the total resistance of the QOD. To adjust the total QOD resistance, [Equation 1](#) can be used:

$$R_{QOD} = R_{PD} + R_{EXT}$$

Where:

- R_{QOD} = Total output discharge resistance
- R_{PD} = Internal pulldown resistance
- R_{EXT} = External resistance placed between the VOUT and QOD pin. (1)
- QOD pin is unused and left floating. Using this method, there will be no quick output discharge functionality, and the output will remain floating after the switch is disabled.

The fall times of the device depend on many factors including the total resistance of the QOD, V_{IN} , and the output capacitance. When QOD is shorted to VOUT, the fall time will change over V_{IN} as the internal R_{PD} varies over V_{IN} . To calculate the approximate fall time of V_{OUT} for a given R_{QOD} , use [Equation 2](#) and [Table 1](#).

$$V_{CAP} = V_{IN} \times e^{-t/\tau}$$

Where:

- V_{CAP} = Voltage across the capacitor (V)
- t = Time since power supply removal (s)
- τ = Time constant equal to $R_{QOD} \times C_L$ (2)

The fall times' dependency on V_{IN} becomes minimal as the QOD value increases with additional external resistance. See [Table 1](#) for QOD fall times.

Table 1. QOD Fall Times

V_{IN} (V)	⁽¹⁾ FALL TIME (μ s) 90% - 10%, $C_{IN} = 1 \mu$ F, $I_{OUT} = 0$ A, $V_{ON} = 0$ V					
	$T_A = 25^\circ\text{C}$			$T_A = 85^\circ\text{C}$		
	$C_L = 1 \mu$ F	$C_L = 10 \mu$ F	$C_L = 100 \mu$ F	$C_L = 1 \mu$ F	$C_L = 10 \mu$ F	$C_L = 100 \mu$ F
5.5	42	190	1880	40	210	2150
5	43	200	1905	45	220	2200
3.3	47	230	2150	50	260	2515
2.5	58	300	2790	60	345	3290
1.8	75	430	4165	80	490	4950
1.2	135	955	9910	135	1035	10980
1	230	1830	19625	210	1800	19270

(1) TYPICAL VALUES WITH QOD SHORTED TO VOUT

8.3.2.1 QOD when System Power is Removed

The adjustable QOD can be used to control the power down sequencing of a system even when the system power supply is removed. When the power is removed, the input capacitor discharges at V_{IN} . Past a certain V_{IN} level, the strength of the R_{PD} will be reduced. If there is still remaining charge on the output capacitor, this will result in longer fall times. For further information regarding this condition, refer to [Shutdown Sequencing During Unexpected System Power Loss](#).

8.3.2.2 Internal QOD Considerations

Special considerations must be taken when using the internal R_{PD} by shorting the QOD pin to the VOUT pin. The internal R_{PD} is a pulldown resistance designed to quickly discharge a load after the switch has been disabled. Care must be used to ensure that excessive current does not flow through R_{PD} during discharge so that the maximum T_J of 125°C is not exceeded. When using only the internal R_{PD} to discharge a load, the total capacitive load must not exceed 200 μF . Otherwise, an external resistor, R_{EXT} , must be used to ensure the amount of current flowing through R_{PD} is properly limited and the maximum T_J is not exceeded. To ensure the device is not damaged, the remaining charge from C_L must decay naturally through the internal QOD resistance and should not be driven.

8.3.3 Adjustable Rise Time (CT)

A capacitor to GND on the CT pin sets the slew rate of V_{OUT} . The CT capacitor will charge up until shortly after the switch is turned on and V_{OUT} becomes stable. Once V_{OUT} become stable, the capacitor will discharge to ground. An approximate formula for the relationship between CT and the slew rate is shown in [Equation 3](#):

$$SR = 0.55 \times CT + 30$$

where

- SR = slew rate (in $\mu s/V$)
- CT = the capacitance value on the CT pin (in pF)
- The units for the constant 30 are $\mu s/V$. The units for the constant 0.52 are $\mu s/(V \times pF)$.

(3)

This equation accounts for 10% to 90% measurement on V_{OUT} and does not apply for CT = 0 pF. Use [Table 2](#) to determine rise times for when CT = 0 pF.

Rise time can be calculated by multiplying the input voltage by the slew rate. [Table 2](#) contains rise time values measured on a typical device.

Table 2. Rise Time Table

CT× (pF)	RISE TIME (μs) 10% - 90%, $C_L = 0.1 \mu F$, $C_{IN} = 1 \mu F$, $R_L = 10 \Omega$ (1)						
	VIN = 5 V	VIN = 3.3 V	VIN = 2.5 V	VIN = 1.8 V	VIN = 1.5 V	VIN = 1.2 V	VIN = 1.0 V
0	135	95	75	60	50	45	40
220	650	455	350	260	220	185	160
470	1260	850	655	480	415	340	300
1000	2540	1680	1300	960	810	660	560
2200	5435	3580	2760	2020	1715	1390	1220
4700	12050	7980	6135	4485	3790	3120	2735
10000	26550	17505	13460	9790	8320	6815	5950

(1) Typical values at 25°C with a 25 V X7R 10% ceramic capacitor on CT.

As the voltage across the capacitor approaches the capacitor rated voltage, the effective capacitance reduces. Depending on the dielectric material used, the voltage coefficient changes. See [Table 3](#) for the recommended minimum voltage rating for the CT capacitor. If using $V_{IN} = 1.2 V$ or 4 V, it is recommended to use the higher of the two CT Voltage ratings specified.

Table 3. Recommended CT Capacitor Voltage Rating

V_{IN} (V)	RECOMMENDED CT CAPACITOR VOLTAGE RATING (V)
1 V to 1.2 V	10
1.2 V to 4 V	16
4 V to 5.5 V	20

8.4 Device Functional Modes

Table 4 describes the connection of the VOUT pin depending on the state of the ON pin.

Table 4. VOUT Connection

ON	QOD CONFIGURATION	TPS22918 VOUT
L	QOD pin connected to VOUT with R_{EXT}	GND (via $R_{EXT}+R_{PD}$)
L	QOD pin tied to VOUT directly	GND (via R_{PD})
L	QOD pin left open	Open
H	Any valid QOD configuration	VIN

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

This section highlights some of the design considerations when implementing this device in various applications. A PSPICE model for this device is also available in the product page of this device on www.ti.com (See the [器件支持](#) section for more information).

9.2 Typical Application

This typical application demonstrates how the TPS22918 can be used to power downstream modules.

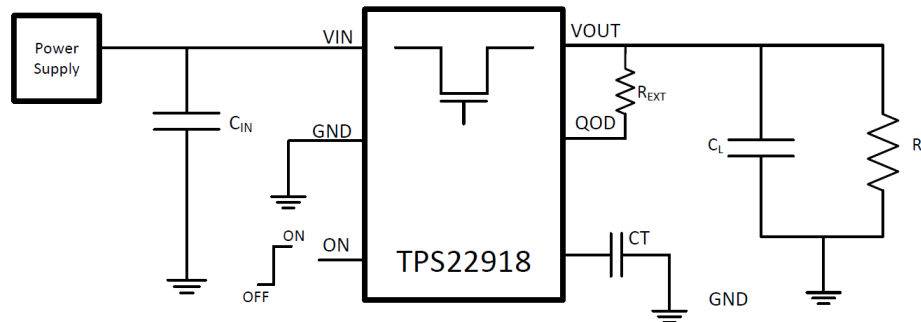


Figure 23. Typical Application Schematic

9.2.1 Design Requirements

For this design example, use the values listed in [Table 5](#) as the design parameters:

Table 5. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
V_{IN}	5 V
Load Current	2 A
C_L	22 μ F
Desired Fall Time	4 ms
Maximum Acceptable Inrush Current	400 mA

9.2.2 Detailed Design Procedure

9.2.2.1 Input Capacitor (C_{IN})

To limit the voltage drop on the input supply caused by transient in-rush currents when the switch turns on into a discharged load capacitor or short-circuit, a capacitor needs to be placed between V_{IN} and GND. A 1 μ F ceramic capacitor, C_{IN} , placed close to the pins, is usually sufficient. Higher values of C_{IN} can be used to further reduce the voltage drop during high-current application. When switching heavy loads, it is recommended to have an input capacitor about 10 times higher than the output capacitor to avoid excessive voltage drop.

9.2.2.2 Output Capacitor (C_L) (Optional)

Because of the integrated body diode in the MOSFET, a C_{IN} greater than C_L is highly recommended. A C_L greater than C_{IN} can cause V_{OUT} to exceed V_{IN} when the system supply is removed. This could result in current flow through the body diode from V_{OUT} to V_{IN} . A C_{IN} to C_L ratio of 10 to 1 is recommended for minimizing V_{IN} dip caused by inrush currents during startup.

9.2.2.3 Shutdown Sequencing During Unexpected System Power Loss

Microcontrollers and processors often have a specific shutdown sequence in which power needs to be removed. Using the adjustable Quick Output Discharge function of the TPS22918, adding a load switch to each power rail can be used to manage the power down sequencing in the event of an unexpected system power loss (i.e. battery removal). To determine the QOD values for each load switch, first confirm the power down order of the device you wish to power sequence. Be sure to check if there are voltage or timing margins that must be maintained during power down. Next, consult QOD Fall Time Table in the [Quick Output Discharge \(QOD\)](#) feature description to determine appropriate C_{OUT} and R_{QOD} values for each power rail's load switch so that the load switches' fall times correspond to the order in which they need to be powered down. In the above example, we would like this power rail's fall time to be 4 ms. Using [Equation 2](#), to determine the appropriate R_{QOD} to achieve our desired fall time.

Because fall times are measured from 90% of V_{OUT} to 10% of V_{OUT} , the equation becomes:

$$.5 V = 4.5 V \times e^{-(4 \text{ ms}) / (R \times (22 \mu\text{F}))} \quad (4)$$

$$R_{QOD} = 83.333 \Omega \quad (5)$$

Refer to [Figure 7](#), R_{PD} at $V_{IN} = 5 \text{ V}$ is approximately 25 Ω . Using [Equation 1](#), the required external QOD resistance can be calculated:

$$83.333 \Omega = 25 \Omega + R_{EXT} \quad (6)$$

$$R_{EXT} = 58.333 \Omega \quad (7)$$

[Figure 24](#) through [Figure 29](#) are scope shots demonstrating an example of the QOD functionality when power is removed from the device (both ON and V_{IN} are disconnected simultaneously). The input voltage is decaying in all scope shots below.

- Initial $V_{IN} = 3.3 \text{ V}$
- QOD = Open, 500 Ω , or shorted to V_{OUT}
- $C_L = 1 \mu\text{F}$, 10 μF
- V_{OUT} is left floating

NOTE: V_{IN} may appear constant in some figures. This is because the time scale of the scope shot is too small to show the decay of C_{IN} .

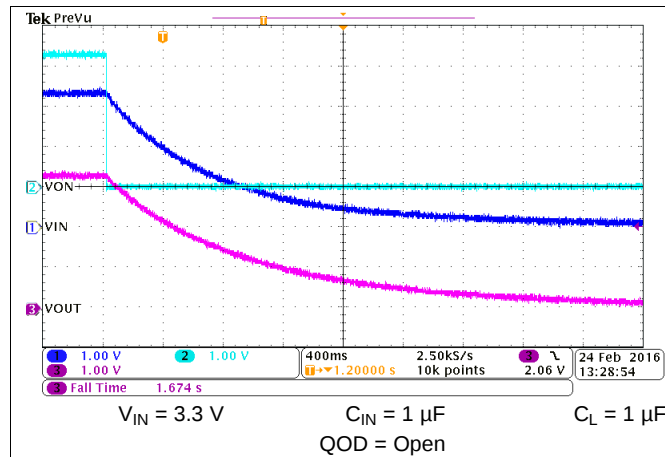


Figure 24. t_F at $V_{IN} = 3.3\text{ V}$

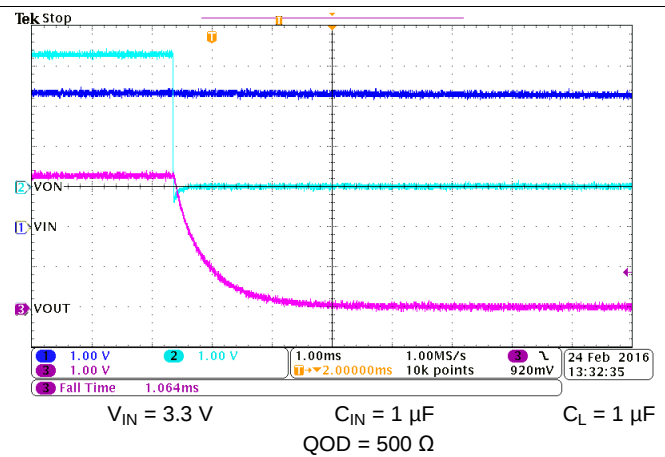


Figure 25. t_F at $V_{IN} = 3.3\text{ V}$

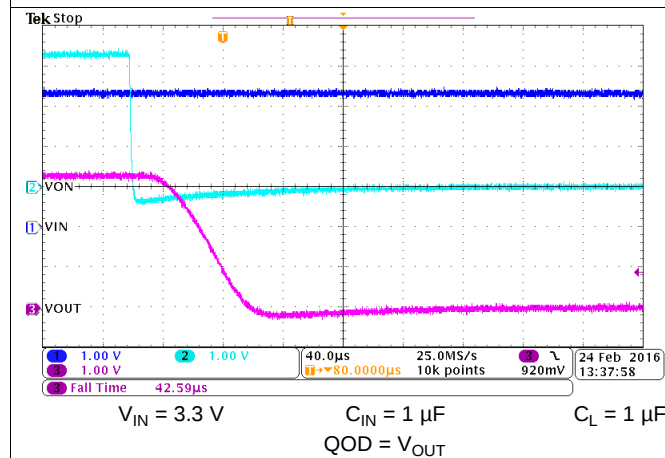


Figure 26. t_F at $V_{IN} = 3.3\text{ V}$

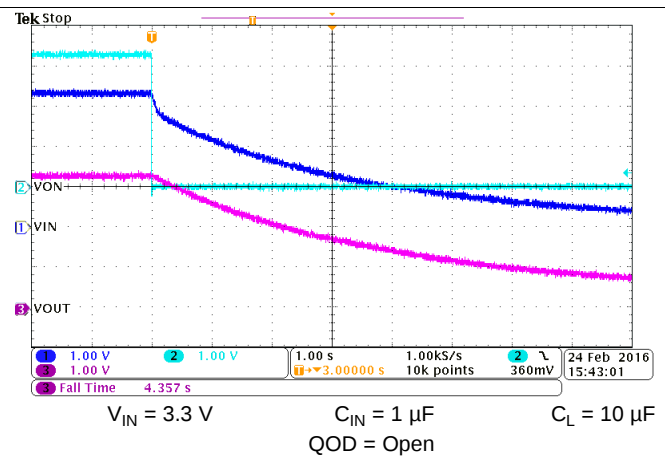


Figure 27. t_F at $V_{IN} = 3.3\text{ V}$

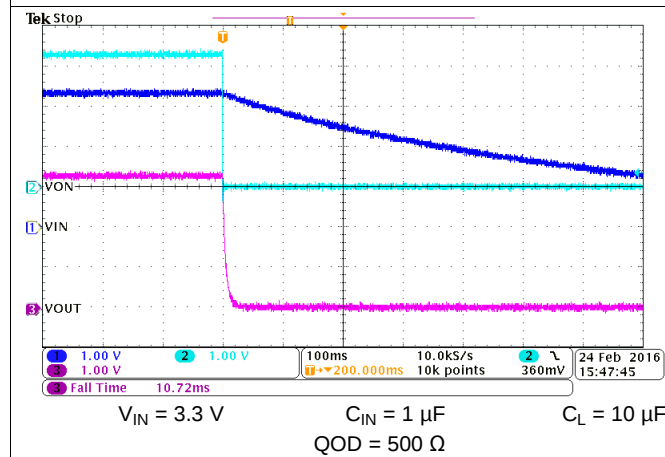


Figure 28. t_F at $V_{IN} = 3.3\text{ V}$

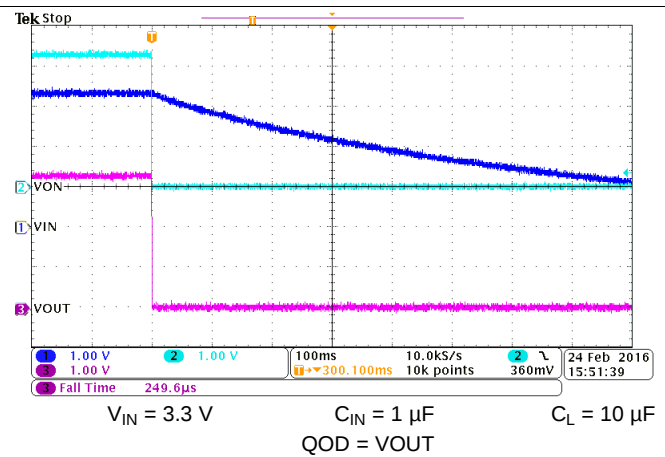


Figure 29. t_F at $V_{IN} = 3.3\text{ V}$

9.2.2.4 VIN to VOUT Voltage Drop

The VIN to VOUT voltage drop in the device is determined by the R_{ON} of the device and the load current. The R_{ON} of the device depends upon the VIN conditions of the device. Refer to the R_{ON} specification of the device in the [Electrical Characteristics](#) table of this data sheet. When the R_{ON} of the device is determined based upon the VIN conditions, use [公式 8](#) to calculate the VIN to VOUT voltage drop:

$$\Delta V = I_{LOAD} \times R_{ON}$$

where

- ΔV = voltage drop from VIN to VOUT
- I_{LOAD} = load current
- R_{ON} = On-resistance of the device for a specific V_{IN}

An appropriate I_{LOAD} must be chosen such that the I_{MAX} specification of the device is not violated. (8)

9.2.2.5 Inrush Current

Use [公式 9](#) to determine how much inrush current will be caused by the C_L capacitor:

$$I_{INRUSH} = C_L \times \frac{dV_{OUT}}{dt}$$

where

- I_{INRUSH} = amount of inrush caused by C_L
- C_L = capacitance on VOUT
- dt = Output Voltage rise time during the ramp up of VOUT when the device is enabled
- dV_{OUT} = change in V_{OUT} during the ramp up of VOUT when the device is enabled (9)

The appropriate rise time can be calculated using the design requirements and the inrush current equation. As we are calculating the rise time (measured from 10% to 90% of V_{OUT}), we will account for this in our dV_{OUT} parameter (80% of $V_{OUT} = 4$ V).

$$400 \text{ mA} = 22 \text{ } \mu\text{F} \times 4 \text{ V}/dt \quad (10)$$

$$dt = 220 \text{ } \mu\text{s} \quad (11)$$

To ensure an inrush current of less than 400 mA, choose a C_T value that will yield a rise time of more than 220 μs . Consulting [Table 2](#) at $V_{IN} = 5$ V, $C_T = 220 \text{ } \mu\text{F}$ will provide a typical rise time of 650 μs . Inputting this rise time and voltage into [公式 9](#), yields:

$$I_{Inrush} = 22 \text{ } \mu\text{F} \times 4 \text{ V} / 650 \text{ } \mu\text{s} \quad (12)$$

$$I_{Inrush} = 135 \text{ mA} \quad (13)$$

This inrush current can be seen in the [Application Curves](#) below. An appropriate C_L value should be placed on VOUT such that the I_{MAX} and I_{PLS} specifications of the device are not violated.

9.2.3 Application Curves

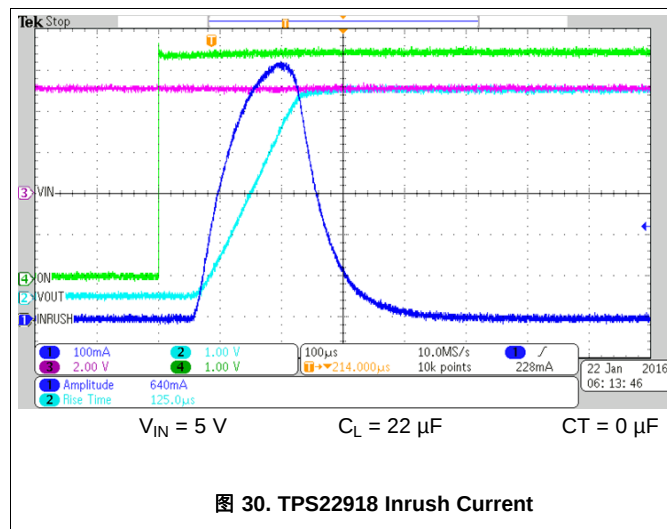


图 30. TPS22918 Inrush Current

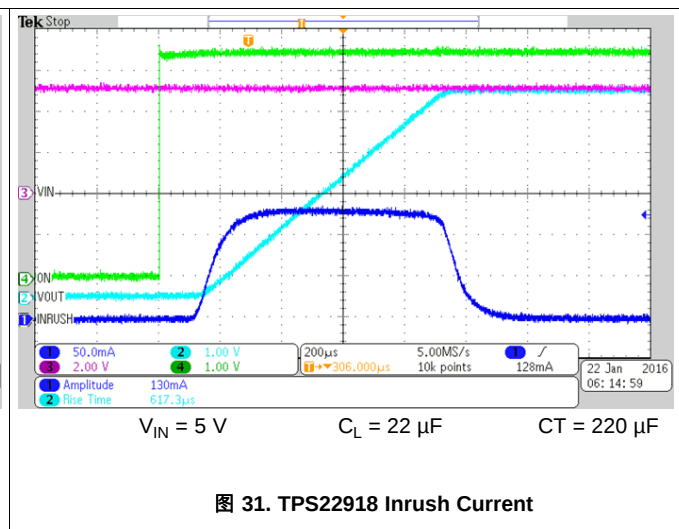


图 31. TPS22918 Inrush Current

10 Power Supply Recommendations

The device is designed to operate from a V_{IN} range of 1 V to 5.5 V. This supply must be well regulated and placed as close to the device terminal as possible with the recommended 1- μF bypass capacitor. If the supply is located more than a few inches from the device terminals, additional bulk capacitance may be required in addition to the ceramic bypass capacitors. If additional bulk capacitance is required, an electrolytic, tantalum, or ceramic capacitor of 1 μF may be sufficient.

The TPS22918 operates regardless of power sequencing order. The order in which voltages are applied to V_{IN} and ON will not damage the device as long as the voltages do not exceed the absolute maximum operating conditions. If voltage is applied to ON before V_{IN} , the slew rate of V_{OUT} will not be controlled.

11 Layout

11.1 Layout Guidelines

V_{IN} and V_{OUT} traces should be as short and wide as possible to accommodate for high current.

The V_{IN} pin should be bypassed to ground with low ESR ceramic bypass capacitors. The typical recommended bypass capacitance is 1- μF ceramic with X5R or X7R dielectric. This capacitor should be placed as close to the device pins as possible.

11.2 Layout Example

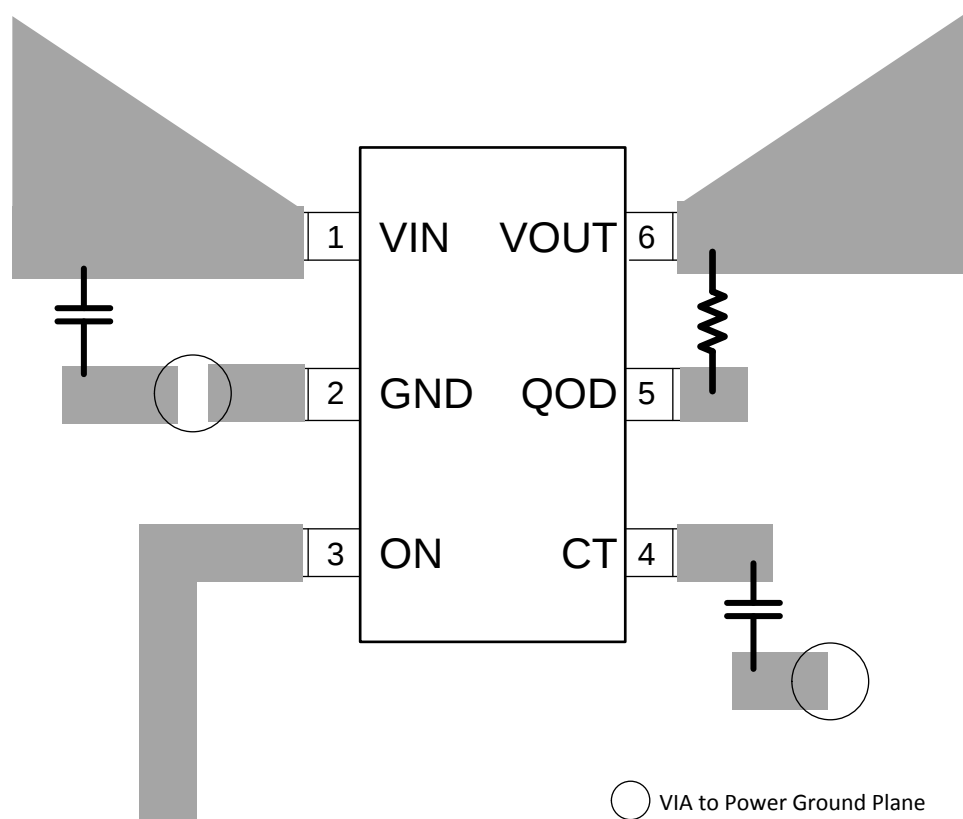


图 32. Recommended Board Layout

11.3 Thermal Considerations

For best performance, all traces should be as short as possible. To be most effective, the input and output capacitors should be placed close to the device to minimize the effects that parasitic trace inductances may have on normal and short-circuit operation. Using wide traces for VIN, VOUT, and GND helps minimize the parasitic electrical effects along with minimizing the case to ambient thermal impedance.

The maximum IC junction temperature should be restricted to 125°C under normal operating conditions. To calculate the maximum allowable dissipation, $P_{D(max)}$ for a given output current and ambient temperature, use 公式 14:

$$P_{D(MAX)} = \frac{T_{J(MAX)} - T_A}{\theta_{JA}}$$

where

- $P_{D(MAX)}$ = maximum allowable power dissipation
- $T_{J(MAX)}$ = maximum allowable junction temperature (125°C for the TPS22918)
- T_A = ambient temperature of the device
- θ_{JA} = junction to air thermal impedance. Refer to the [Thermal Information](#) table. This parameter is highly dependent upon board layout.

(14)

12 器件和文档支持

12.1 器件支持

12.1.1 开发支持

关于 TPS22918 PSpice 瞬态模型，请参见 [SLVMBI6](#)。

12.2 文档支持

12.2.1 相关文档

相关文档如下：

《TPS22918 5.5V、2A、导通电阻为 50mΩ 的负载开关评估模块》，[SLVUAP0](#)。

12.3 社区资源

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](#), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.4 商标

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

12.5 静电放电警告



这些装置包含有限的内置 ESD 保护。存储或装卸时，应将导线一起截短或将装置放置于导电泡棉中，以防止 MOS 门极遭受静电损伤。

12.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。这些信息是针对指定器件可提供的最新数据。这些数据会在无通知且不对本文档进行修订的情况下发生改变。欲获得该数据表的浏览器版本，请查阅左侧的导航栏。

重要声明

德州仪器(TI) 及其下属子公司有权根据 JESD46 最新标准, 对所提供的产品和服务进行更正、修改、增强、改进或其它更改, 并有权根据 JESD48 最新标准中止提供任何产品和服务。客户在下订单前应获取最新的相关信息, 并验证这些信息是否完整且是最新的。所有产品的销售都遵循在订单确认时所提供的TI 销售条款与条件。

TI 保证其所销售的组件的性能符合产品销售时 TI 半导体产品销售条件与条款的适用规范。仅在 TI 保证的范围内, 且 TI 认为 有必要时才会使用测试或其它质量控制技术。除非适用法律做出了硬性规定, 否则没有必要对每种组件的所有参数进行测试。

TI 对应用帮助或客户产品设计不承担任何义务。客户应对其使用 TI 组件的产品和应用自行负责。为尽量减小与客户产品和应用相关的风险, 客户应提供充分的设计与操作安全措施。

TI 不对任何 TI 专利权、版权、屏蔽作品权或其它与使用了 TI 组件或服务的组合设备、机器或流程相关的 TI 知识产权中授予 的直接或隐含权限作出任何保证或解释。TI 所发布的与第三方产品或服务有关的信息, 不能构成从 TI 获得使用这些产品或服务 的许可、授权、或认可。使用此类信息可能需要获得第三方的专利权或其它知识产权方面的许可, 或是 TI 的专利权或其它 知识产权方面的许可。

对于 TI 的产品手册或数据表中 TI 信息的重要部分, 仅在没有对内容进行任何篡改且带有相关授权、条件、限制和声明的情况 下才允许进行复制。TI 对此类篡改过的文件不承担任何责任或义务。复制第三方的信息可能需要服从额外的限制条件。

在转售 TI 组件或服务时, 如果对该组件或服务参数的陈述与 TI 标明的参数相比存在差异或虚假成分, 则会失去相关 TI 组件 或服务的所有明示或暗示授权, 且这是不正当的、欺诈性商业行为。TI 对任何此类虚假陈述均不承担任何责任或义务。

客户认可并同意, 尽管任何应用相关信息或支持仍可能由 TI 提供, 但他们将独力负责满足与其产品及其应用中使用的 TI 产品 相关的所有法律、法规和安全相关要求。客户声明并同意, 他们具备制定与实施安全措施所需的全部专业技术和知识, 可预见 故障的危险后果、监测故障及其后果、降低有可能造成人身伤害的故障的发生机率并采取适当的补救措施。客户将全额赔偿因 在此类安全关键应用中使用任何 TI 组件而对 TI 及其代理造成的任何损失。

在某些场合中, 为了推进安全相关应用有可能对 TI 组件进行特别的促销。TI 的目标是利用此类组件帮助客户设计和创立其特 有的可满足适用的功能安全性标准和要求的终端产品解决方案。尽管如此, 此类组件仍然服从这些条款。

TI 组件未获得用于 FDA Class III (或类似的生命攸关医疗设备) 的授权许可, 除非各方授权官员已经达成了专门管控此类使 用的特别协议。

只有那些 TI 特别注明属于军用等级或“增强型塑料”的 TI 组件才是设计或专门用于军事/航空应用或环境的。购买者认可并同 意, 对并非指定面向军事或航空航天用途的 TI 组件进行军事或航空航天方面的应用, 其风险由客户单独承担, 并且由客户独 力负责满足与此类使用相关的所有法律和法规要求。

TI 已明确指定符合 ISO/TS16949 要求的产品, 这些产品主要用于汽车。在任何情况下, 因使用非指定产品而无法达到 ISO/TS16949 要求, TI 不承担任何责任。

	产品		应用
数字音频	www.ti.com.cn/audio	通信与电信	www.ti.com.cn/telecom
放大器和线性器件	www.ti.com.cn/amplifiers	计算机及周边	www.ti.com.cn/computer
数据转换器	www.ti.com.cn/dataconverters	消费电子	www.ti.com.cn/consumer-apps
DLP® 产品	www.dlp.com	能源	www.ti.com.cn/energy
DSP - 数字信号处理器	www.ti.com.cn/dsp	工业应用	www.ti.com.cn/industrial
时钟和计时器	www.ti.com.cn/clockandtimers	医疗电子	www.ti.com.cn/medical
接口	www.ti.com.cn/interface	安防应用	www.ti.com.cn/security
逻辑	www.ti.com.cn/logic	汽车电子	www.ti.com.cn/automotive
电源管理	www.ti.com.cn/power	视频和影像	www.ti.com.cn/video
微控制器 (MCU)	www.ti.com.cn/microcontrollers		
RFID 系统	www.ti.com.cn/rfidsys		
OMAP应用处理器	www.ti.com.cn/omap		
无线连通性	www.ti.com.cn/wirelessconnectivity	德州仪器在线技术支持社区	www.deyisupport.com

邮寄地址: 上海市浦东新区世纪大道1568号, 中建大厦32楼邮政编码: 200122
Copyright © 2016, 德州仪器半导体技术(上海)有限公司

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS22918DBVR	ACTIVE	SOT-23	DBV	6	3000	RoHS & Green	NIPDAU SN	Level-2-260C-1 YEAR	-40 to 105	13MW	Samples
TPS22918DBVT	ACTIVE	SOT-23	DBV	6	250	RoHS & Green	NIPDAU SN	Level-2-260C-1 YEAR	-40 to 105	13MW	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



SOT-23 - 1.45 mm max height

Technical drawing of a mechanical part showing three views: front, side, and end view.

Front View Dimensions:

- Overall width: 3.0 (2.6)
- Overall height: 3.05 (2.75)
- Left side features: 1.9, 2X 0.95, 1.75 (1.45)
- Right side features: 6, 5, 4
- Bottom features: 6X 0.50 (0.25), 3
- Pin 1 Index Area (hatched)
- Feature Callouts: A, B, C

Side View Dimensions:

- Maximum width: 1.45 MAX
- Typical width: (1.1)

End View Dimensions:

- Gage Plane: 0.25
- Seating Plane
- Typical width: 0.6 (0.3)
- Typical height: 0.22 (0.08)
- Angle: 8° (0°) TYP

Surface Texture: 0.2 RMS

NOTES:

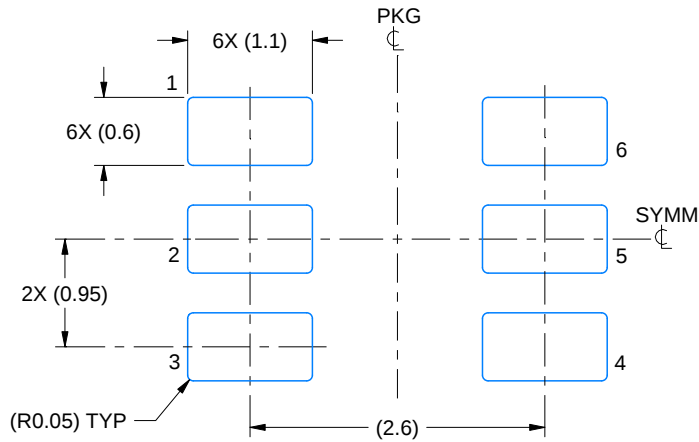
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
4. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
5. Reference JEDEC MO-178.

EXAMPLE BOARD LAYOUT

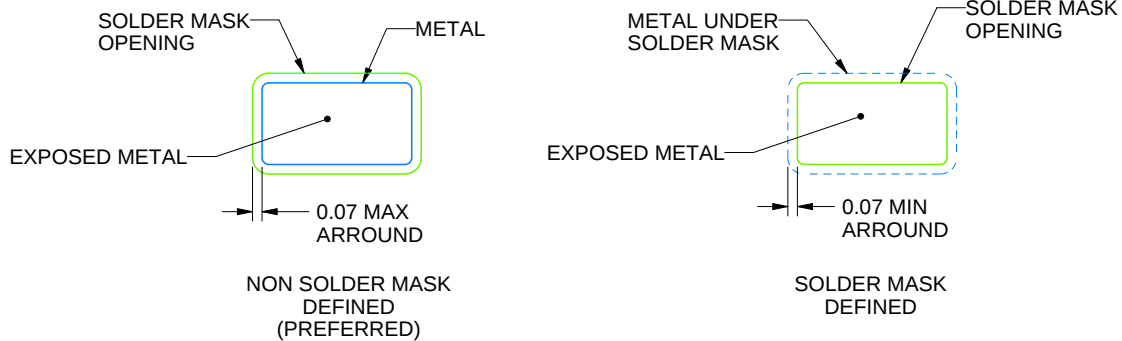
DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4214840/B 03/2018

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

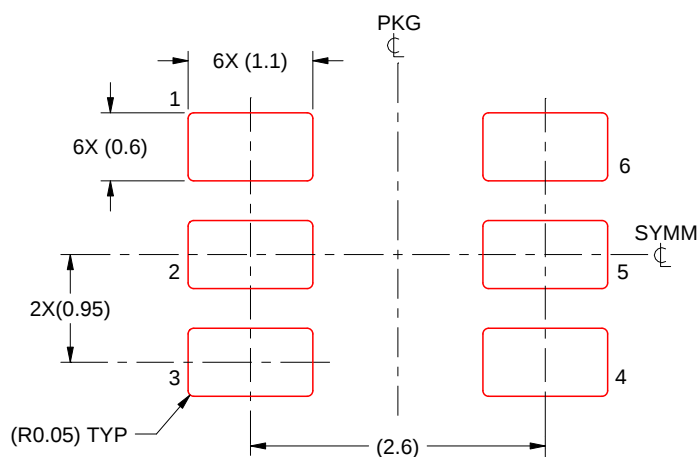
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214840/B 03/2018

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要声明和免责声明

TI 均以“原样”提供技术性 & 可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证其中不含任何瑕疵，且不做任何明示或暗示的担保，包括但不限于对适销性、适合某特定用途或不侵犯任何第三方知识产权的暗示担保。

所述资源可供专业开发人员应用 TI 产品进行设计使用。您将对以下行为独自承担全部责任：(1) 针对您的应用选择合适的 TI 产品；(2) 设计、验证并测试您的应用；(3) 确保您的应用满足相应标准以及任何其他安全、安保或其他要求。所述资源如有变更，恕不另行通知。TI 对您使用所述资源的授权仅限于开发资源所涉及 TI 产品的相关应用。除此之外不得复制或展示所述资源，也不提供其它 TI 或任何第三方的知识产权授权许可。如因使用所述资源而产生任何索赔、赔偿、成本、损失及债务等，TI 对此概不负责，并且您须赔偿由此对 TI 及其代表造成的损害。

TI 所提供产品均受 TI 的销售条款 (<http://www.ti.com.cn/zh-cn/legal/termsofsale.html>) 以及 [ti.com.cn](http://www.ti.com.cn) 上或随附 TI 产品提供的其他可适用条款的约束。TI 提供所述资源并不扩展或以其他方式更改 TI 针对 TI 产品所发布的可适用的担保范围或担保免责声明。

邮寄地址：上海市浦东新区世纪大道 1568 号中建大厦 32 楼，邮政编码：200122
Copyright © 2020 德州仪器半导体技术（上海）有限公司